

Copper Bath SLOTOCOUP CU 110

IMDS ID No. 736943

Copper Bath SLOTOCOUP CU 110 has been specifically developed to optimise the benefits of periodic reverse pulse plating on a continual production basis.

Copper Bath SLOTOCOUP CU 110 deposits fine grained, ductile coatings with excellent metal distribution.

Make up of the electrolyte requires two additives but only one additive is required for the operation of the bath, which is Copper Bath Additive SLOTOCOUP CU 114 that was especially developed for this system.

Combining Copper Bath SLOTOCOUP CU 110 with periodic reverse pulse plating may shorten the plating time significantly with an excellent metal distribution at the same time.

SLOTOCOUP CU 110 also deposits bright, fine grained ductile copper coatings when operated as a DC-plating electrolyte.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read these instructions carefully and follow recommendations given.

We reserve the right to make technical changes as necessary.

In the interests of safety, please pay attention to the R- and S- phrases on the drum label.

The shelf life of the additives is generally 18 months.

The date of production is taken from the first 3 figures of the batch number.

Figure 1 = year; figures 2-3 = month; figures 4-7 = batch number; (UK labels use a 4 digit year code).

For the storage of chemical products only the Hazardous Substances Regulation must be followed.

The Hazardous Goods Regulation (ADR/GGVS) are only valid for transportation and must not be applied to storage.